

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chang-Hwang HUA</td> <td>05/23/2013</td> </tr> <tr> <td>Chih-Hsien LIN</td> <td>05/22/2013</td> </tr> </tbody> </table>		Name	Execution Date	Chang-Hwang HUA	05/23/2013	Chih-Hsien LIN	05/22/2013
Name	Execution Date						
Chang-Hwang HUA	05/23/2013						
Chih-Hsien LIN	05/22/2013						
RECEIVING PARTY DATA							
Name:	WIN SEMICONDUCTORS CORP.						
Street Address:	No. 69, Technology 7th Rd.						
Internal Address:	Hwaya Technology Park, Kuei Shan Hsiang						
City:	Tao Yuan Shien						
State/Country:	TAIWAN						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13968797</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13968797		
Property Type	Number						
Application Number:	13968797						
CORRESPONDENCE DATA							
Fax Number:	7036217155						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
Phone:	703 621 7140						
Email:	mailroom@mg-ip.com						
Correspondent Name:	Joe McKinney Muncy						
Address Line 1:	4000 Legato Road						
Address Line 2:	Suite 310						
Address Line 4:	Fairfax, VIRGINIA 22033						
ATTORNEY DOCKET NUMBER:	5900/0378PUS1						
NAME OF SUBMITTER:	Joe McKinney Muncy						
Signature:	/Joe McKinney Muncy/						
Date:	08/23/2013						
Total Attachments: 3 source=2013-08-23-Assignment#page1.tif source=2013-08-23-Assignment#page2.tif source=2013-08-23-Assignment#page3.tif							

OP \$40.00 13968797

Attorney Docket No.
5900/0378PUS1

MUNCY, GEISSLER, OLDS & LOWE, PLLC

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

COMBINED DECLARATION AND ASSIGNMENT

Title of Invention: Structure of a Semiconductor Chip with Substrate Via Holes and Metal Bumps and a Fabrication Method Thereof

As a below named inventor, I hereby declare that:

This declaration is directed to:

The attached application; or

United States application number or PCT international application number _____,
filed on _____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Direct all correspondence to the address associated with Customer Number 60601.

WHEREAS, WIN SEMICONDUCTORS CORP. of No. 69, Technology 7th Rd., Hwaya Technology Park, Kuei Shan Hsiang, Tao Yuan Shien, Taiwan, R.O.C., its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and in any foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these

presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional, conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Muncy, Geissler, Olds & Lowe, PLLC the power to insert on this Assignment any further identification which may be necessary or

desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

LEGAL NAME OF FIRST OR SOLE INVENTOR:

Chang-Hwang HUA

Signature: Chang Hwa Date: 5/23/13

LEGAL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY:

Chih-Hsien LIN

Signature: Chih - Hsien Lin Date: 2013/05/22

LEGAL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY:

Signature: _____ Date: _____

LEGAL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY:

Signature: _____ Date: _____

Additional inventors are being named on separately numbered sheets attached hereto.